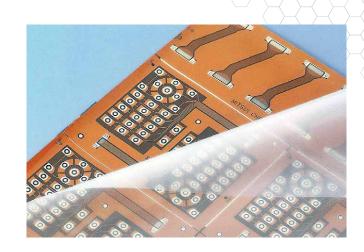


TPX[™] release film with the pliability to closely follow substrate surfaces

TPX[™] release film maintains a superb balance of heat resistance and releasability, and can be applied to complex, uneven surfaces. Used to produce flexible printed circuits (FPC), TPX[™] release film improves yield and productivity in factories around the world. Further, TPX[™] is used in a variety of high performance applications including food wrap and release film to produce advanced materials.



Benefits of Using TPX™



TPX[™] has excellent releasability which improves yield and productivity.

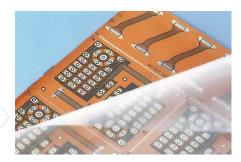


TPX™ has a melting point of 220 °C to 240 °C and can be used in high temperature production processes.



TPX[™] features higher gas permeability than other resins due to its unique molecular structure. When product freshness is critical, packaging film produced with TPX[™] is an excellent choice.

Case Studies



Release film for the production of Flexible Printed Circuits (FPC)



Release film for a variety of advanced materials



Heat Resistant Wrap

Mitsui Chemicals, Inc.

Head Office: TPX & MILLION Dept. Performance Polymers Div.

Shiodome City Center, 5-2, Higashi-Shimbashi 1-chome, Minato-ku, Tokyo 105-7122

Osaka Branch: Functional Polymer Department, Functional Resin Division

Shinanobashi Mitsui Bldg. 8F, 11-7, Utsubohonmachi 1-chome, Nishi-ku, Osaka 550-0004

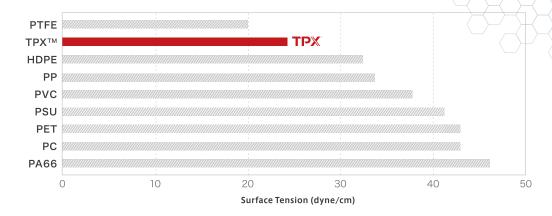




Release Film

Releasability

TPX[™] surface tension is equivalent to that of PTFE, and offers excellent releasability.



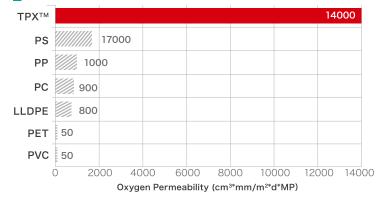
Heat Resistance

TPX™ film has high heat resistance and can be used for food wrap or as an industrial film.

Heat Resistance Comparison	Melting Points		
ТРХТМ	220°C~240°C		
PVDC	140°C		
PE	110°C		



Gas Permeability



TPX[™] has excellent gas permeability because of its molecular structure.

Although TPX[™] is an imperforate film, it features gas permeability equivalent to microporous film.

Note: With the cooperation of Mitsui Chemicals Tohcello, Inc. Opulent™ (http://www.mc-tohcello.co.jp/english/product/industry/tpx.html)

Product / Processing Guide

Туре	Grade	C1[°C]	C2~C5[℃]	AD[℃]	Dice C1 [°C]	Resin Temperature[℃]
High Rigidity	RT18	280	290~300	300	300~310	310
Moderate Rigidity	MX004	270	280~290	290	290~300	300
Low Rigidity	MX002	260	270~280	280	280~290	290

Molding Machine

Device: T die-cast film-forming machine/Die: opening length 600 mm/Screw: ϕ 50 mm, L/D = 28, C/R = 3.0 [barrier screw type]/Chill roll temperature: 60°C

The data described in this leaflet are representative examples of measurement values obtained using our test methods. The described data and evaluations are not guaranteed. Prior to application to your products, please evaluate the practicality and confirm that there are no problems.

